Features

• Long life and robust package

• Variety of lens types available

ullet Package: 1500pcs / reel

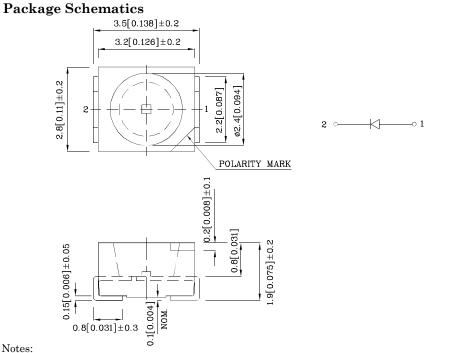
 \bullet Moisture sensitivity level : level 3

www.SunLEDusa.com

• RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		THI (GaAlAs)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	50	mA	
Forward Current (Peak) 1/100 Duty Cycle 10us Pulse Width	ifs	1200	mA	
Power Dissipation	P_D	80	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	$^{\circ}\mathrm{C}$	
Storage Temperature	Tstg	-40 ~ +85	C	

Operating Characteristics (T _A =25°C)		THI (GaAlAs)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	1.6	V
Reverse Current (Max.) $(V_R=5V)$	$I_{ m R}$	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λΡ	880	nm
Spectral Line Full Width At Half-Maximum (Typ.) $(I_F=20\text{mA})$	$\triangle \lambda$	50	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	90	pF

Part Number	Emitting Material	Lens-color	Radiant Intensity (Po=mW/sr) @20mA		Wavelength nm λΡ	Viewing Angle 20 1/2
			min.	typ.		
XZTHI45S	GaAlAs	Water Clear	1.2	1.8	880	120°

Apr 19,2011

XDSB5013 V2 Layout: Maggie L.



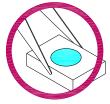
3.5x2.8 mm INFRARED EMITTING DIODE

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

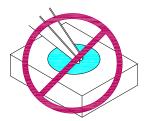
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

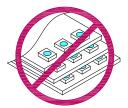


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

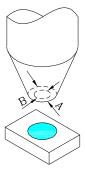




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

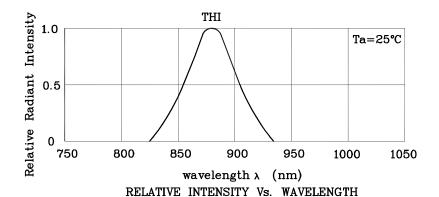


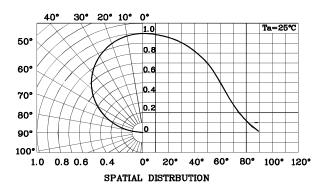
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Apr 19,2011 XDSB5013 V2 Layout: Maggie L.

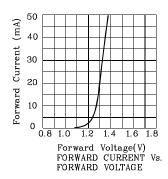


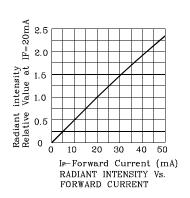


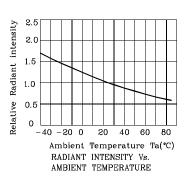




♦ THI

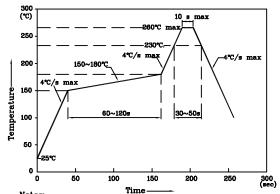






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

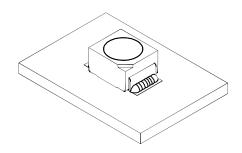


- notes:
 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

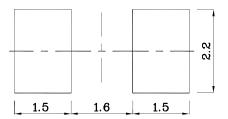




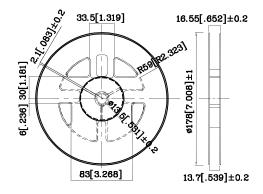
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



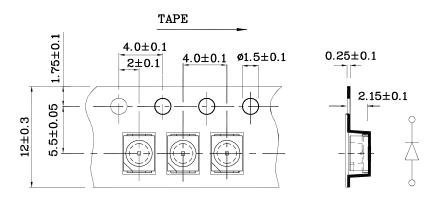
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



* Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux), the typical accuracy of the sorting process is as follows:

- 1. Radiant Intensity / Luminous Flux: +/-15%
- 2. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters





PACKING & LABEL SPECIFICATIONS

